

DESCRIPTION

~~WORKPIECE CUTTING METHOD~~

TECHNICAL FIELD

[0001]

The present invention relates to a method for slicing workpiece using a wire saw.

BACKGROUND ART

[0002]

In recent years, enlargement of semiconductor wafers has been demanded, and a wire saw is exclusively used for slicing workpieces.

The wire saw is a device that enables a wire (a high tensile steel wire) to travel at high speed, and presses a workpiece (e.g., a silicon ingot) against the wire to be sliced while applying slurry to the wire so that many wafers are simultaneously sliced out (see Patent Document 1).

[0003]

Here, FIG. 6 is a schematic view showing of an example of a conventional general wire saw.

As shown in FIG. 6, a wire saw 101 is mainly constituted of a wire 102 configured to slice a workpiece, a wire guide 103 around which the wire 102 is wound, a tension giving mechanism 104 configured to give tension to the wire 102, workpiece feeding means 105 configured to feed the workpiece to be sliced, a nozzle 106 configured to supply slurry obtained by dispersing and mixing abrasive grains such as SiC fine powder in a coolant at the time of slicing, and others.

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[0004]